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Teramount and AMF announces their collaboration to enable scalable silicon photonics packaging

Teramount and AMF have successfully integrated silicon photonics process for implementing Teramount's PhotonicBump™ technology on AMF's silicon photonics wafers. Photonic-bumps incorporate wafer level optics for enabling unique packaging and test capabilities including wide-band surface coupling geometry, efficient spot size convertor to single-mode fiber and wafer level testing capabilities on WDM silicon photonic wafers.

The PhotonicBump™ technology will be provided as part of the AMF offering. Customers will benefit from scalable fiber packaging through PhotonicPlug™ connectivity, optimized for large assembly tolerances, passive assembly protocols and high-volume manufacturing capabilities.

This will enhance the existing AMF Packaging Service Portfolio to offer comprehensive low-cost solutions to our customers.

For more details, please contact our Sales team: sales@advmf.com